

## AG-800

### Polymer Thick Film

#### Description

AG-800 Silver Conductive Ink is a general purpose, silver-filled, electrically conductive ink for high-speed screen printing. Suitable for standard printed circuit applications, low temp heaters and crossover printing. It is compatible with PriElex UV curable dielectrics, conductive epoxy adhesives and UV curable component encapsulants.

#### Key Features

- Can withstand short-term temperature of solder bath process
- Tough, scuff resistant surface. Outstanding crease resistance
- Thin with solvent for spraying or dipping for EMI/RFID shielding applications
- Can be blended with carbon ink to obtain intermediate resistance values
- Compatible with PriElex UV curable dielectrics, conductive epoxy adhesives and UV curable component encapsulants



*This picture does not show the packaging of AG-800 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms*

#### Typical Properties

Viscosity	5.2-5.7 kcps. Brookfield SC4-14 spindle @ SR 20, 25°C
Solids	54-58%
Metal	Ag
Color	Silver

<25 μ

#### Recommended Processing Guide

Printing Parameters	Monofilament polyester (157 to 230 mesh) or stainless steel (165-325 mesh) is recommended
Recommended Thinner	Solvent 30

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#### Warranty

6 months

#### Storage

Store at ambient conditions away from direct light. Material should be thoroughly mixed or rolled on a jar roller at a slow speed for 1 hour prior to use

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